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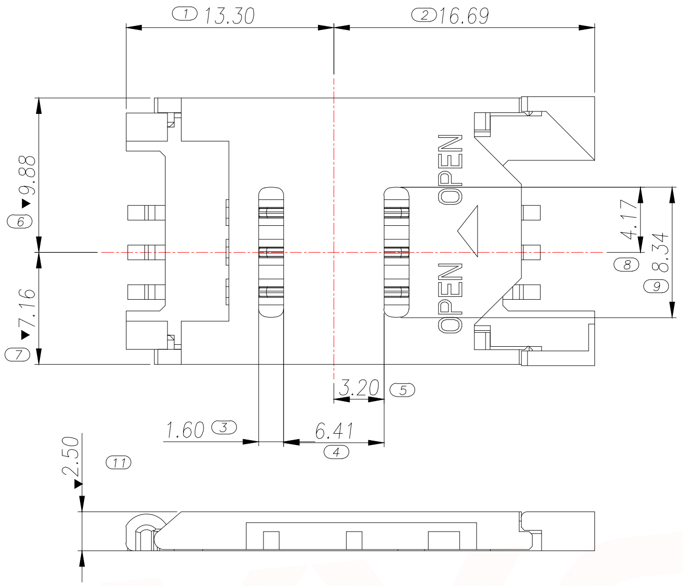
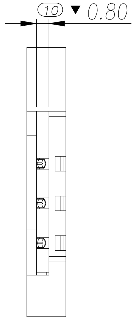
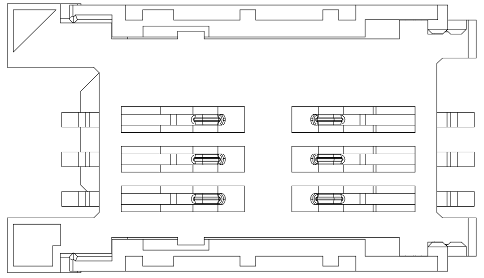
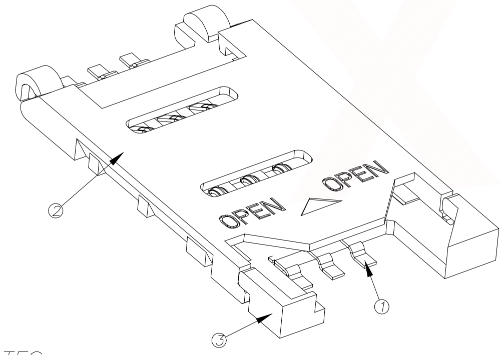
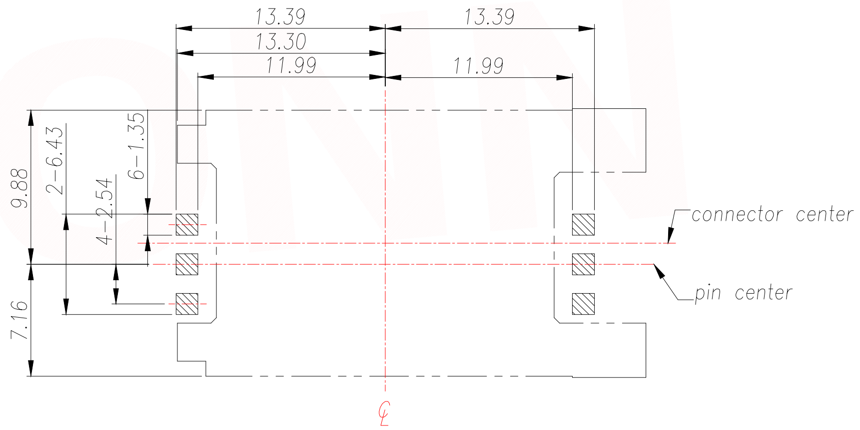
REV.	Q'TY	ECN. NO.	APR.	DATE











RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED MATAL MASK T=0.12mm

▨ SMT SOLDER AREA
▩ NO PATTERN AND VIA HOLE IN HTIS AREA

NOTES:
1)MATERIAL:
HOUSING: THERMOPLASTIC,UL 94V-0, COLOR:BLACK
CONTACT: COPPER ALLOY
2)FINISH
CONTACT: GOLD FLASH
SOLDER AREA: TIN 100u" Min
3)Solder-ability
IR reflow:250°C,5sec.Max
Manual soldering:350°C ,3sec.max

1	Contact	COPPER ALLOY	Gold FLASH	6	
2	Cover	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
3	Housing	THERMOPLASTIC,UL 94V-0, COLOR:BLACK		1	
ITEM	NAME	MATERIIAL	FINISH	Q'ty	REMARK

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyeconn Electronics Co.,Ltd	
TOLERANCE UNLESS OTHERWISE SPECIFIED			
.X±0.35	X.°± 5°	APR. Alex	TITLE: 2.5H 6PIN HINGE MICRO SIM CARD CONNECTOR
.XX±0.25	.X°± 3°	CHK. Jack	DWG NO. SIM101-FWB6AH2.5
.XXX±0.15	.XX°± 1°	DRA. Can	PROJ. CUSTOMER DRAWING SIZE A4 SCALE 1:1 SHEET 1/1 REV. A